Semiconductor Device Type: V2X-TQFP-64-10x10x1mm-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				21.50	100.00%	7.50%		
	Silicon	7440-21-3	21.50		100.00%		7.50%	74994
Plating and Anode Ball				3.58	100.00%	1.25%		
	Tin	7440-31-5	3.58		99.90%		1.25%	12475
	Miscellaneous	Trade Secret	0.00		0.10%		0.00%	12
Mold Compound				228.79	100.00%	79.80%		
	Silica (Fused)	60676-86-0	186.46		81.50%		65.04%	650402
	Phenolic Resin	Trade Secret	18.30		8.00%		6.38%	63843
	Epoxy Resin	Trade Secret	22.88		10.00%		7.98%	79804
	Carbon Black	1333-86-4	1.14		0.50%		0.40%	3990
Bond Wire				0.57	100.00%	0.20%		
	Gold	7440-57-5	0.57		100.00%		0.20%	1988
Die Attach				2.15	100.00%	0.75%		
	Silver	7440-22-4	1.46		68.00%		0.51%	5100
	Carbocyclic Acrylate	Trade Secret	0.43		20.00%		0.15%	1500
	Bismaleimide Resin	Trade Secret	0.11		5.00%		0.04%	375
	Acrylate	Trade Secret	0.11		5.00%		0.04%	375
	Epoxycyclohexylethyltrimethoxysilane	3388-04-3	0.02		1.00%		0.01%	75
	Palladium Compound	Trade Secret	0.02		1.00%		0.01%	75
Lead Frame				28.20	100.00%	9.84%		
	Copper	7440-50-8	27.08		96.01%		9.44%	94447
	Magnesium	7439-95-4	0.05		0.17%		0.02%	164
	Silicon	7440-21-3	0.20		0.69%		0.07%	682
	Nickel	7440-02-0	0.88		3.13%		0.31%	3083
Lead Frame Plating				1.90	100.00%	0.66%		
	Silver	7440-22-4	1.90		100.00%		0.66%	6614
Totals			**286.69**	**286.69**		**100.00%**	**100.00%**	**1000000**